

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN THE MATTER OF: KIM et al  
SERIAL NO: 10/553,647  
FILED: October 14, 2005  
TITLE: RESIN COMPOSITION FOR MOLD USED IN FORMING  
MICROPATTERN, AND...  
GROUP: 4151  
CONFIRMATION NO: 5573  
EXAMINER: Ryan M. Ochylski

**R E S P O N S E**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

SIR:

This is in response to the outstanding office communication dated November 3, 2008. Applicant respectfully requests that any insufficient fees be deducted from our deposit account 504581.

Please amend the application as follows: